

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>John S. Guzek</td><td>03/11/2010</td></tr><tr><td>Vijay K. Nair</td><td>03/12/2010</td></tr></tbody></table>	Name	Execution Date	John S. Guzek	03/11/2010	Vijay K. Nair	03/12/2010					
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RECEIVING PARTY DATA											
<table border="1"><tr><td>Name:</td><td>Intel Corporation</td></tr><tr><td>Street Address:</td><td>2200 Mission College Blvd.</td></tr><tr><td>City:</td><td>Santa Clara</td></tr><tr><td>State/Country:</td><td>CALIFORNIA</td></tr><tr><td>Postal Code:</td><td>95052</td></tr></table>	Name:	Intel Corporation	Street Address:	2200 Mission College Blvd.	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95052	
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PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12725925</td></tr></tbody></table>	Property Type	Number	Application Number:	12725925							
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CORRESPONDENCE DATA											
Fax Number: (612)332-8352 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone: 503-712-3485											
Email: amaiti@cpaglobal.com											
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Address Line 2: P.O. Box 52050											
Address Line 4: Minneapolis, MINNESOTA 55402											
ATTORNEY DOCKET NUMBER:	P32899										
NAME OF SUBMITTER:	John N. Greaves										
Total Attachments: 4 source=P32899_Executed_Assignment#page1.tif source=P32899_Executed_Assignment#page2.tif source=P32899_Executed_Assignment#page3.tif source=P32899_Executed_Assignment#page4.tif											

CH \$40.00 12725925

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PATENT  
REEL: 026160 FRAME: 0045

## **ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**JOHN S. GUZEK; VIJAY K. NAIR**

hereby sell, assign, and transfer to:

### **Intel Corporation**

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

### **SYSTEM-IN-PACKAGE USING EMBEDDED-DIE CORELESS SUBSTRATES, AND PROCESSES OF FORMING SAME**

**(I hereby authorize and request my attorney, associated with Customer Number 59796, to insert on the designated lines below, the filing date and application number of said application when known.)**

which was filed on March 17, 2010 as  
United States Application Number 12/725,925 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and

*Attorney Docket No.: P32899*

improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

John S. Gurski

(Today's Date)

Vijay K. Nair

(Today's Date)

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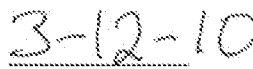
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John S. Guzek

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(Today's Date)

  
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Vijay K. Nair

  
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(Today's Date)